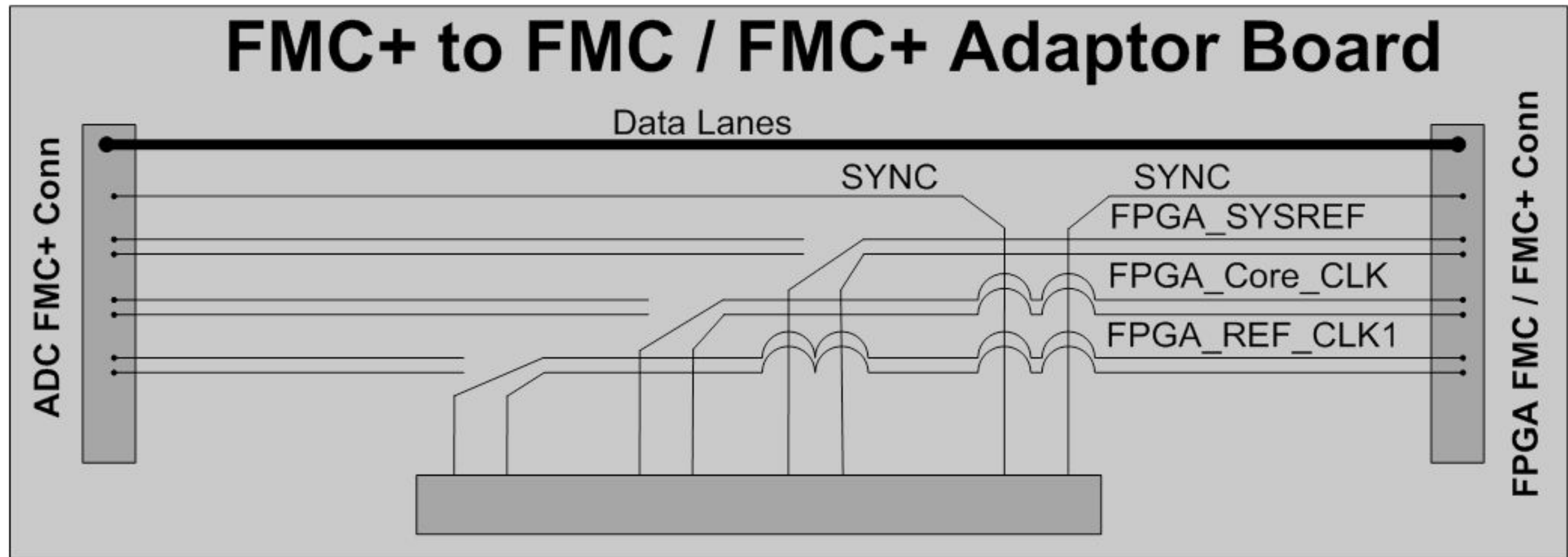


Revision History

Rev	ECN #	Approved Date	Approved by	Notes
N/A	N/A	N/A	N/A	N/A

# FMC+ to FMC / FMC+ Adaptor Board

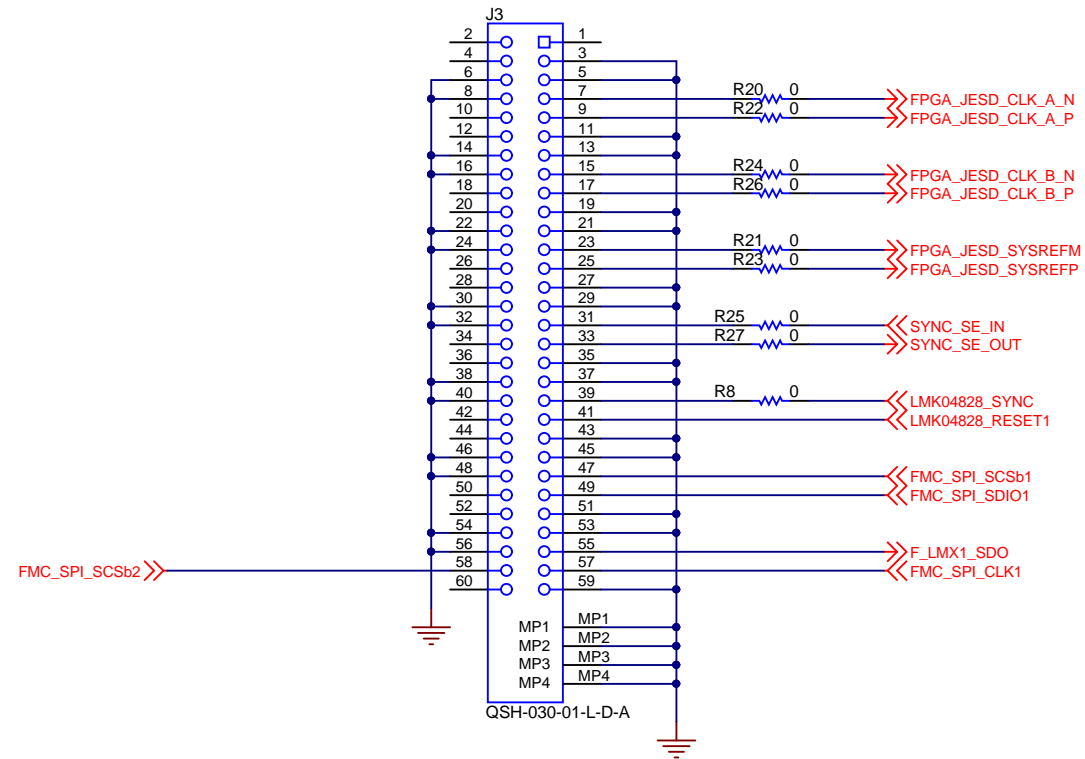


Note: J2 is compatible for TSW14J56 and J4 is compatible for TSW14J57.

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Orderable: NA	Designed for: Public Release	Mod. Date: 9/11/2017
TID #: 01021	Project Title: FMC+ TO FMC	
Number: FMC+ TO FMC Rev: E2	Sheet Title:	
SVN Rev: Not in version control	Assembly Variant: [No Variations]	Sheet: 1 of 6
Drawn By:	File: TIDA-01021_FMC+ TO FMC Adapter Card_CoverSheet.SchDoc	http://www.ti.com
Engineer: Ajeet Pal	Contact: http://www.ti.com/support	© Texas Instruments 2017

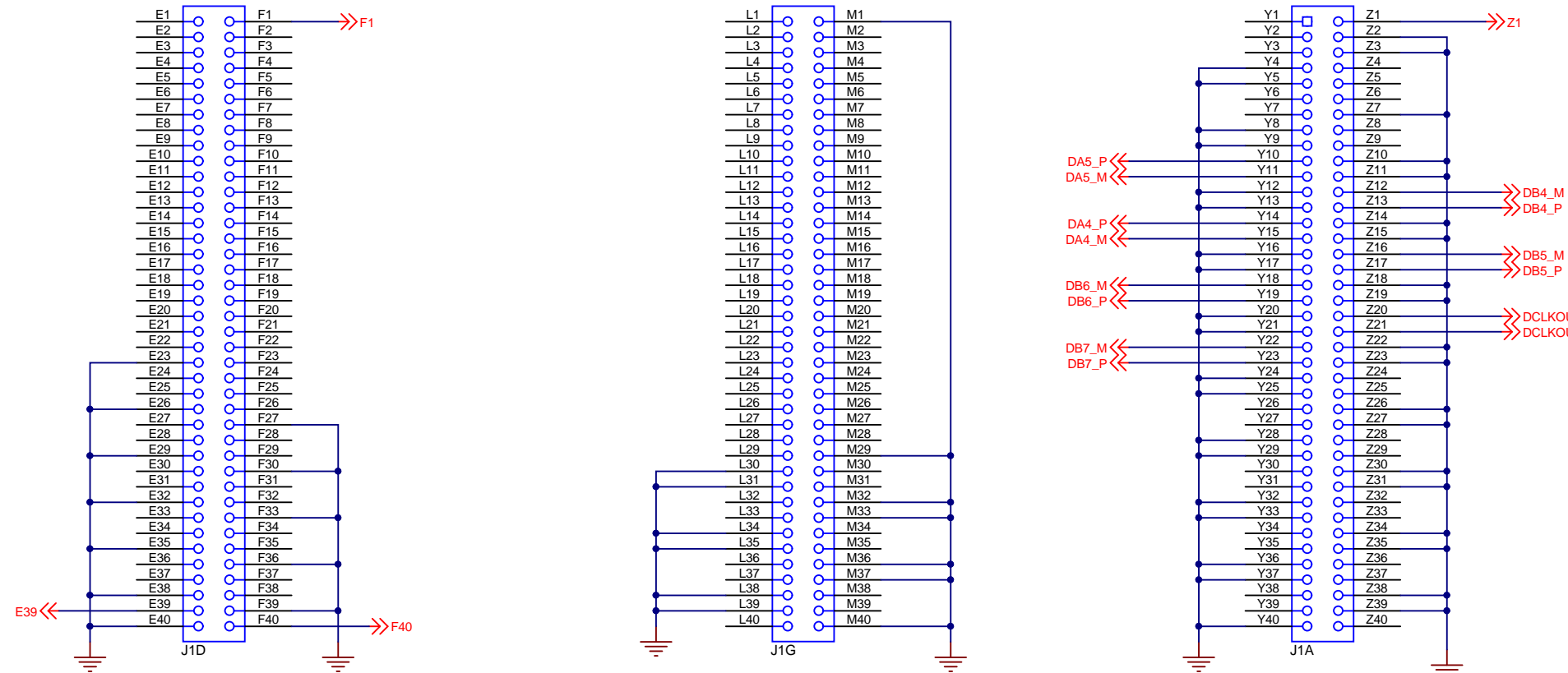
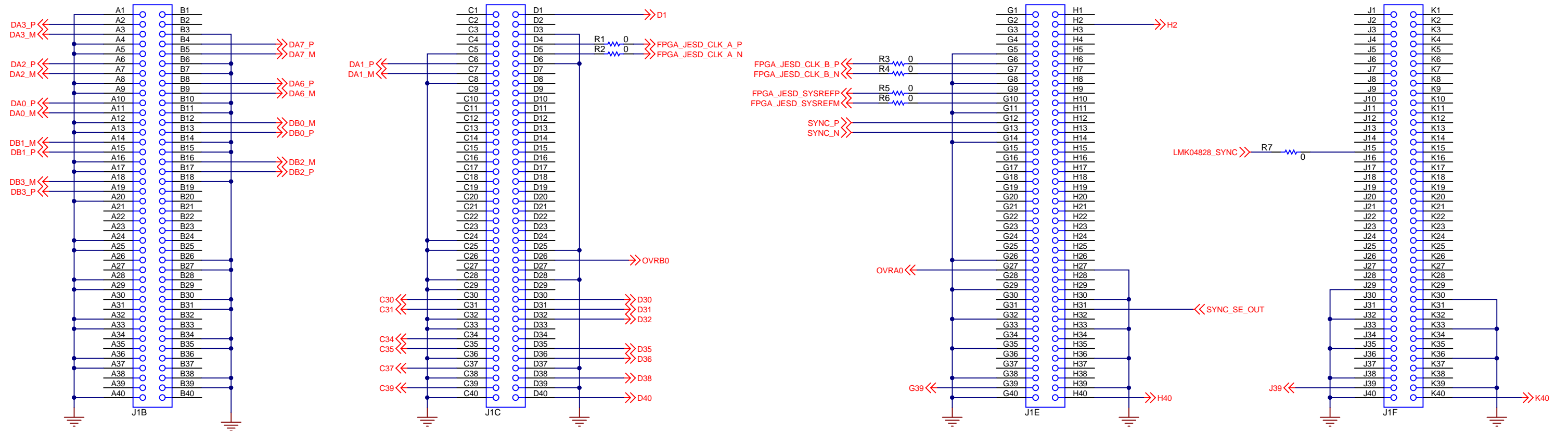




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Orderable: NA	Designed for: Public Release	Mod. Date: 7/14/2017
TID #: 01021	Project Title: FMC+ TO FMC	
Number: FMC+ TO FMC Rev: E2	Sheet Title:	
SVN Rev: Not in version control	Assembly Variant: [No Variations]	Sheet: 2 of 6
Drawn By: Avinash N	File: TIDA-01021_TIDA-01021_FMC+ TO FMC Adapter Board	Sheet: 1 of 6
Engineer: Ajeet Pal	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	

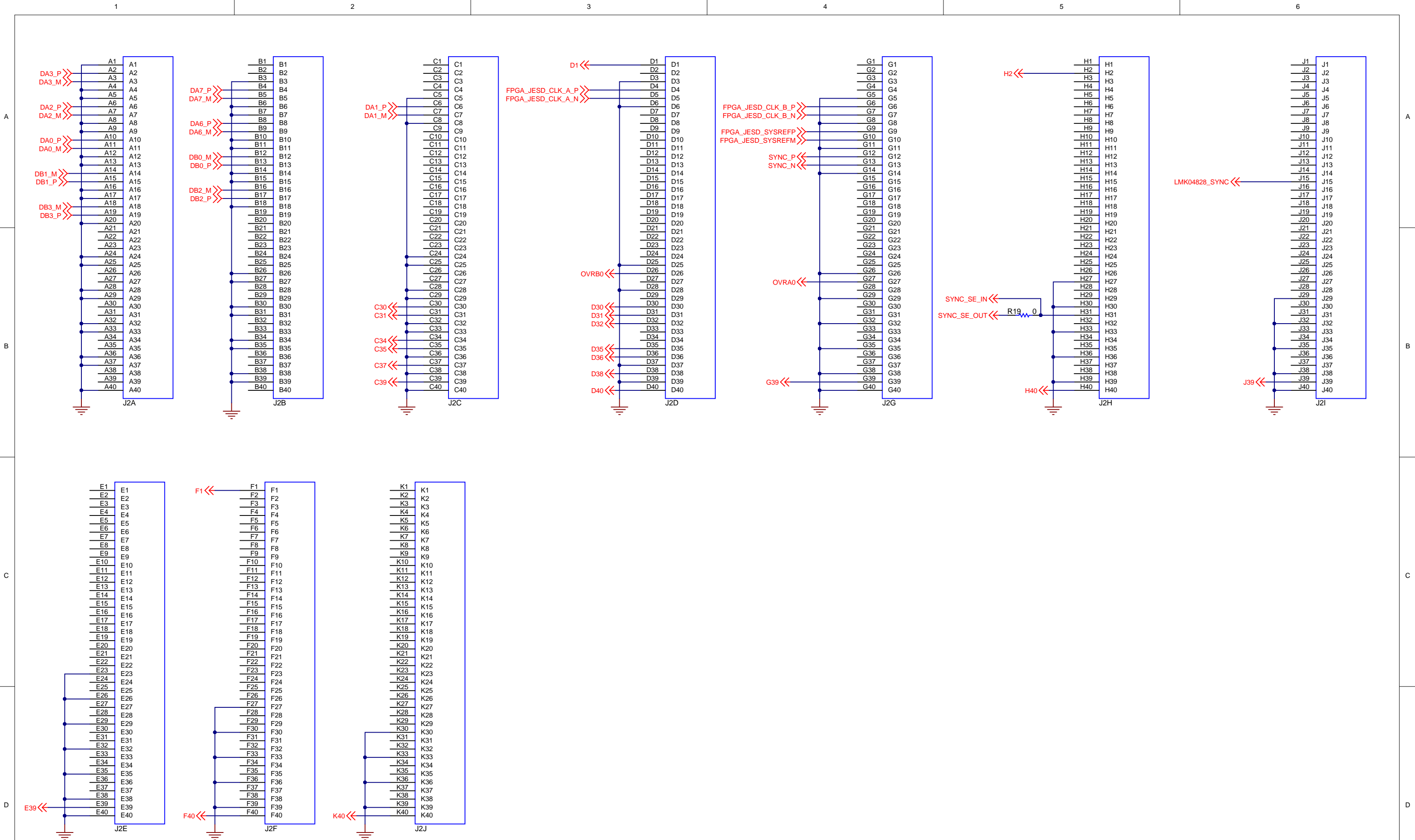




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Orderable: NA	Designed for: Public Release	Mod. Date: 7/14/2017
TID #: 01021	Project Title: FMC+ TO FMC	
Number: FMC+ TO FMC Rev: E2	Sheet Title:	
SVN Rev: Not in version control	Assembly Variant: [No Variations]	Sheet: 3 of 6
Drawn By: Avinash N	File: TIDA-01021_FMC+ TO FMC Adapter Card_Sheet3.DOC	http://www.ti.com
Engineer: Ajeet Pal	Contact: http://www.ti.com/support	© Texas Instruments 2017

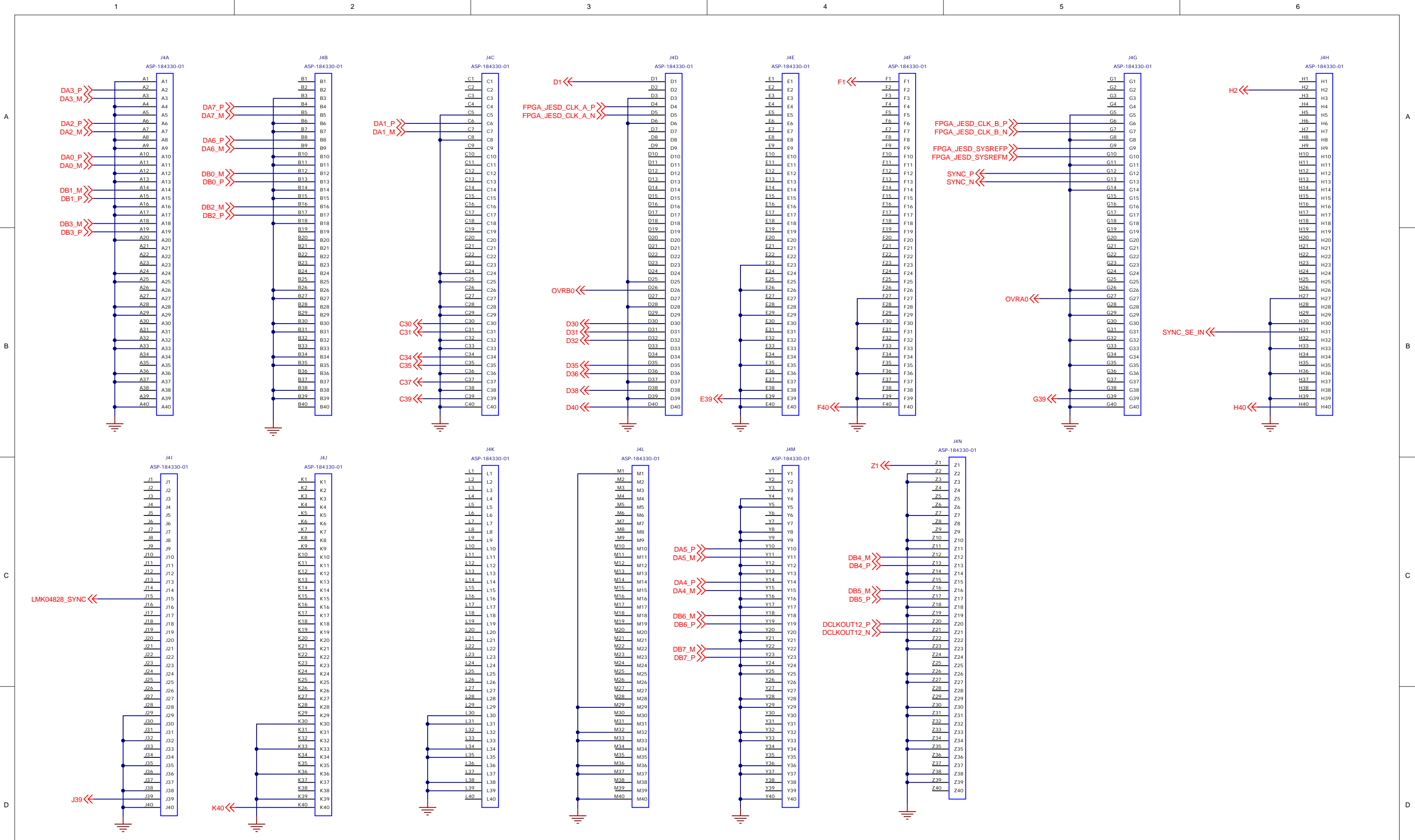




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Orderable: NA	Designed for: Public Release	Mod. Date: 7/14/2017
TID #: 01021	Project Title: FMC+ TO FMC	
Number: FMC+ TO FMC Rev: E2	Sheet Title:	
SVN Rev: Not in version control	Assembly Variant: [No Variations]	Sheet: 4 of 6
Drawn By: Avinash N	File: TIDA-01021_FMC+ TO FMC Adapter Card_Sheet 4 of 6.Doc	
Engineer: Ajeet Pal	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	





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Orderable: NA	Designed for: Public Release	Mod. Date: 7/14/2017
TID #: 01021	Project Title: FMC+ TO FMC	
Number: FMC+ TO FMC Rev: E2	Sheet Title:	
SVN Rev: Not in version control	Assembly Variant: [No Variations]	Sheet: 5 of 6
Drawn By: Avinash N	File: TIDA-01021_FMC+ TO FMC Adapter Card_Sheet 5 of 6.Doc	
Engineer: Ajeet Pal	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	



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A

A



PCB Number: FMC+ TO FMC  
PCB Rev: E2

PCB LOGO  
Logo1

PCB LOGO  
Pb-Free Symbol

PCB LOGO  
FCC disclaimer

**A** You should delete the nylon screws/standoffs and/or the bumpons as needed for your design (or substitute other parts from Hardware.IntLib). Bumpons are cheaper, but provide less clearance.

Deleting anything else from this page may result in your EVM submission being rejected (until you add them back).

Update the Label Text in the Label Table as needed for each Assembly Variant.

You should delete this note too.

B

B

Variant/Label Table	
Variant	Label Text
001	ChangeMe!
002	ChangeMe!

LBL1  
PCB Label  
Size: 0.65" x 0.20"

ZZ1  
Label Assembly Note  
This Assembly Note is for PCB labels only

ZZ2  
Assembly Note  
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3  
Assembly Note  
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4  
Assembly Note  
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

C

C

D

D

Orderable: NA	Designed for: Public Release	Mod. Date: 7/14/2017
TID #: 01021	Project Title: FMC+ TO FMC	
Number: FMC+ TO FMC Rev: E2	Sheet Title:	
SVN Rev: Not in version control	Assembly Variant: [No Variations]	Sheet: 6 of 6
Drawn By:	File: TIDA-01021_FMC+ TO FMC Adapter Card_Half Size SchDoc	http://www.ti.com
Engineer: Ajeet Pal	Contact: http://www.ti.com/support	

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